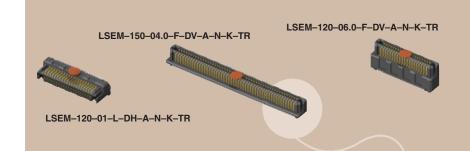


(0,80mm) .0315" **LSEM SERIES** 





## **HIGH SPEED HERMAPHRODITIC STRIP**

## **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?LSEM

Insulator Material: Black Liquid Crystal

Polymer

Contact Material:

Phosphor Bronze

Phosphor Bronze Plating: Au or Sn over 50µ" (1,27µm) Ni Current Rating: 1.2A @ 95°C ambient (6 positions powered)

Operating Temp Range: -55°C to +125°C RoHS Compliant:

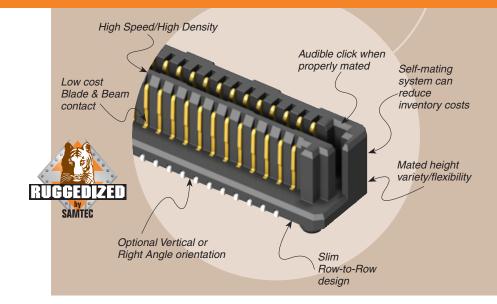
## **Processing:**

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x Lead-Free Solderable:

SMT Lead Coplanarity: (0,10mm) .004" max Board Stacking:

For applications requiring more than two connectors per board, contact ipg@samtec.com

Mates with: **LSEM** 

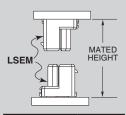


NO. PINS PER ROW **LEAD PLATING** OPTION

OPTION



## APPLICATION



LEAD STYLE	MATED HEIGHT*
-03.0 & -03.0	(6,00) .236
-03.0 & -04.0	(7,00) .276
-04.0 & -04.0	(8,00) .315
-03.0 & -06.0	(9,00) .354
-04.0 & -06.0	(10,00) .394
-06.0 & -06.0	(12,00) .472
*Processing conditions will affect mated height.	

Note: Some lengths, styles and options are non-standard, non-returnable, 20, 30, 40, 50

Specify LEAD STYLE from chart

LEAD

STYLE -01

-DH only

-03.0

-04.0

-06.0

= Gold flash on contact, Matte Tin on tail

=10µ" (0,25µm) Gold on contact Matte Tin on tail

В Α

(1,50) 4,45)

177

NA NA

.175 .059

5,45) (2,50)

.215 .098

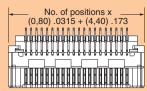
7,45) (4,50)

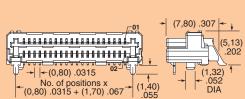
-DV = Vertical -DH = Right Angle

(Lead style -01 only)

= (5,50mm) .217" DIA Polyimide film Pick & Place Pad

> -TR = Tape & Reel





-DH-N

